

<b>INFORMATION DISCLOSURE STATEMENT</b>		Atty. Docket No.: 150.00800102		Serial No.: 09/651,702			
		Applicant(s): Brian A. VAARTSTRA					
		Filing Date: August 30, 2000		Group: 1756			
#4 <b>U.S. PATENT DOCUMENTS</b>							
Examiner Initial		Document Number	Date	Name	Class	SubClass	Filing Date If Appropriate
MB		4,296,146	10/20/81	Penn	427	38	
		4,778,536	10/18/88	Grebinski	134	36	
		4,861,424	08/29/89	Fujimura et al.	156	643	
		4,944,837	07/31/90	Nishikawa et al.	156	643	
		5,013,366	05/07/91	Jackson et al.	134	1	
		5,037,506	08/06/91	Gupta et al.	156	643	
		5,298,112	03/29/94	Hayasaka et al.	156	643	
		5,382,316	01/17/95	Hills et al.	156	643	
		5,401,322	03/28/95	Marshall	134	13	
		5,403,436	04/04/95	Fujimura et al.	156	643	
		5,643,474	7/1/97	Sangeeta	216	96	
		5,651,860	07/29/97	Li	156	643	
		6,024,801	02/15/00	Wallace et al.	134	1	
MB		6,149,828	11/20/00	Vaartstra	216	57	
<b>FOREIGN PATENT DOCUMENTS</b>							
		Document Number	Date	Country	Class	SubClass	Translation
							Yes No
MB		WO 95/20476	08/03/95	PCT			
<b>OTHER DOCUMENTS (Including Authors, Title, Date, Pertinent Papers, etc.)</b>							
MB		G. Bakker et al., "Removal of Thermally Grown Silicon Dioxide Films Using Water at Elevated Temperature and Pressure", <u>J. Electrochem. Soc.</u> , 142(11), 3940-3944 (1995).					
MB		M. Dax, "Removing Photoresist Without Plasmas or Liquid Strippers," <u>Semiconductor International: Contamination Control News</u> , 52 (September 1996).					
MB		Deal et al., "Vapor Phase Wafer Cleaning: Processing for the 1990s," <u>Solid State Technology</u> , 73-77 (July 1990).					
MB		T. Nolan, "Economic Geology and the Bulletin of the Society of Economic Geologists", 45(7), Title Page, Table of Contents, pgs. 601, 629-653 (1950).					
<b>EXAMINER</b> <i>Michelle G. ...</i>				<b>Date Considered</b> 2/21/02			
*Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.							